

REMARKS/ARGUMENTS

The applicant's attorneys appreciate the Examiner's thorough search and remarks.

Fig. 8 has been amended. Amended Fig. 8 is consistent with the original Fig. 8 as filed, as well as the specification.

No new matter has been added.

Acceptance of amended Fig. 8 is requested.

Claim 1 has been rejected as obvious over Kurz, U.S. Patent No. 4,395,673 or Applicant Admitted Prior Art (AAPA) in view of Beihoff et al. (Beihoff) U.S. Patent Publication No. 2003/0133267. Reconsideration is requested.

Claim 1 has been amended and now calls for the following combination:

1. An integrated active rectifier module comprising;

a base plate;

a plurality of substrates attached to one surface of said base plate each with a respective flexible adhesive;

a heatsink in thermal contact with said base plate and positioned opposite said substrates;

power elements for an active rectifier for supplying recharging power to a battery of an automobile, said active rectifier being mounted on one substrate, and including a plurality of active rectification circuits each connectable to a respective phase of a stator to rectify the power output thereof;

metallic conductive blocks on said one substrate to serve as raised pads, said conductive blocks being connected to corresponding leads disposed above said one substrate;

elements for a voltage regulator to regulate the output voltage of said stator, said voltage regulator being mounted on another substrate; and

elements for driving said power elements mounted on another substrate.

An example of the claimed combination is disclosed in the specification, paragraphs [0077], [0082]. As explained in the specification, conductive blocks "serve as raised bond pads that allow for easier processing and durability". See paragraph [0082].

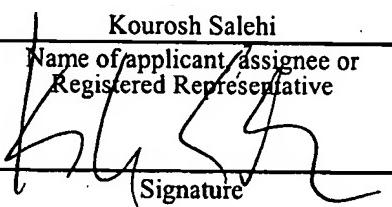
Beihoff on the other hand does not teach or suggest using conductive blocks on the substrate that serve as raised pads "connected to corresponding leads above said one substrate" as set forth in claim 1. The remaining references do not disclose a module arrangement and thus cannot cure the deficiency of Beihoff. It is respectfully submitted, therefore, that claim 1 is not obvious over the art of record. Reconsideration is requested.

Furthermore, regarding claims 2-4, it is submitted that Beihoff does not teach a lead frame supported over the substrates or the base plate. If the Examiner disagrees a more specific reference to a lead frame meeting the limitations of claims 2-4 is requested for the record. Otherwise, withdrawal of the rejections is requested.

Regarding claims 5 and 6, Beihoff does not teach a second lead frame "supported above said lead frame" in which the first lead frame is used for connection to "a phase of a stator" and the second lead frame to serve as an "output". If the Examiner disagrees, a more specific reference to a second lead frame as defined in claims 5 and 6 is requested for the record. Otherwise, withdrawal of the rejections is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

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Respectfully submitted,



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